

RAMMon v1.1 Build: 1000 built with SysInfo v1.0 Build: 1132 PassMark (R)

Software - www.passmark.com

Number of Memory Devices: 1 Total Physical Memory: 7607 MB (8192 MB)

Total Available Physical Memory: 1572 MB

Memory Load: 79%

Item	Slot #1	Slot #2
Ram Type	DDR4	Not Populated
Maximum Clock Speed (MHz)	1333 (JEDEC)	
Maximum Transfer Speed (MHz)	DDR4-2666	
Maximum Bandwidth (MB/s)	PC4-21300	
Memory Capacity (MB)	8192	
Jedec Manufacture Name	SK Hynix	
Search Amazon.com	Search!	
SPD Revision	1.1	
Registered	No	
ECC	No	
DIMM Slot #	1	
Module Part #	HMA81GS6CJR8N-VK	
Module Revision	0x0	
Module Serial #	0x32940C0F	
Module Manufacturing Location	1	
# of Row Addressing Bits	16	
# of Column Addressing Bits	10	
# of Banks	16	
# of Ranks	1	
Device Width in Bits	8	
Bus Width in Bits	64	
Module Voltage	1.2V	
CAS Latencies Supported	10 11 12 13 14 15 16 17 18 19 20	
Timings @ Max Frequency (JEDEC)	19-19-19-43	
Maximum frequency (MHz)	1333	
Maximum Transfer Speed (MHz)	DDR4-2666	
Maximum Bandwidth (MB/s)	PC4-21300	
Minimum Clock Cycle Time, tCK (ns)	0.750	
Minimum CAS Latency Time, tAA (ns)	13.750	
Minimum RAS to CAS Delay, tRCD (ns)	13.750	
Minimum Row Precharge Time, tRP (ns)	13.750	

Minimum Active to Precharge Time, tRAS (ns)	32.000
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Minimum Row Active to Row Active Delay, tRRD (ns)	3.000	
Minimum Auto-Refresh to Active/Auto-Refresh Time, tRC (ns)	45.750	
Minimum Auto-Refresh to Active/Auto-Refresh Command Period, tRFC (ns)	350.000	
DDR4 Specific SPD Attributes		
Maximum Clock Cycle Time, tCKmax (ns)	1.600	
Minimum Auto-Refresh to Active/Auto-Refresh Command Period, tRFC2 (ns)	260.000	
Minimum Auto-Refresh to Active/Auto-Refresh Command Period, tRFC4 (ns)	160.000	
Minimum Activate to Activate Delay Time different bank group, tRRD_Smin (ns)	3.000	
Minimum Activate to Activate Delay Time same bank group, tRRD_Lmin (ns)	4.900	
Minimum CAS to CAS Delay Time same bank group, tCCD_Lmin (ns)	5.000	
Minimum Four Activate Window Delay (ns)	21.000	
Maximum Activate Window in units of tREFI	8192	
Thermal Sensor Present	No	
DRAM Stepping	255	
DRAM Manufacture	SK Hynix	
SDRAM Package Type	Monolithic, 1 die, Single load stack	
Maximum Activate Count (MAC)	Unlimited MAC	
Post Package Repair Supported	No	
Module Type	SO-DIMM	
Module Height (mm)	30	
Module Thickness (front), (mm)	2	
Module Thickness (back), (mm)	2	
Reference Raw Card Used	Raw Card A Rev. 16	

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